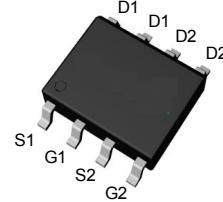


Dual Enhancement Mode MOSFET (N-and P-Channel)

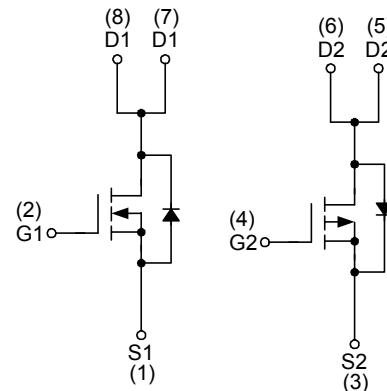
Features

- **N Channel**
40V/7.5A,
 $R_{DS(ON)} = 21m\Omega$ (max.) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 25m\Omega$ (max.) @ $V_{GS} = 4.5V$
- **P Channel**
-40V/-5.5A,
 $R_{DS(ON)} = 38m\Omega$ (max.) @ $V_{GS} = -10V$
 $R_{DS(ON)} = 62m\Omega$ (max.) @ $V_{GS} = -4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

Pin Description



Top View of SOP-8



N-Channel MOSFET P-Channel MOSFET

Applications

- Synchronous Rectification
- Motor Control
- Fan Pre-driver H-bridge

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		N Channel	P Channel	Unit
Common Ratings					
V_{DSS}	Drain-Source Voltage		40	-40	V
V_{GSS}	Gate-Source Voltage		± 20	± 20	V
T_J	Maximum Junction Temperature		150		$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 150		$^\circ\text{C}$
I_S	Diode Continuous Forward Current		2	-2	A
I_{DP}	Pulse Drain Current Tested	$V_{GS}=10\text{V(N)}, V_{GS}=-10\text{V(P)}$	30	-22	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	7.5	-5.5	A
		$T_A=70^\circ\text{C}$	6	-4.5	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2	2	W
		$T_A=70^\circ\text{C}$	1.3	1.3	
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	Steady State	50	50	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	62.5	62.5	$^\circ\text{C/W}$
		Steady State ^b	110	110	
I_{AS}^a	Avalanche Current, Single pulse	$L=0.5\text{mH}$	10	10	A
E_{AS}^a	Avalanche Energy, Single pulse	$L=0.5\text{mH}$	25	25	mJ

Note a : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_j=25^\circ\text{C}$).

Note b : Surface Mounted on 1in^2 pad area, $t = 999\text{sec}$.

N Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	N Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=32\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_J=85^\circ\text{C}$	-	-	30	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	1.5	2	2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
$R_{\text{DS(ON)}}^{\text{c}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{DS}}=6\text{A}$	-	16	21	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{DS}}=5\text{A}$	-	18	25	
Diode Characteristics						
V_{SD}^{c}	Diode Forward Voltage	$I_{\text{SD}}=1\text{A}, V_{\text{GS}}=0\text{V}$	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	$I_{\text{DS}}=6\text{A}, dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	-	13	-	ns
Q_{rr}	Reverse Recovery Charge		-	8.7	-	nC
Dynamic Characteristics ^d						
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	2.5	-	Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}, \text{Frequency}=1.0\text{MHz}$	-	815	-	pF
C_{oss}	Output Capacitance		-	95	-	
C_{rss}	Reverse Transfer Capacitance		-	60	-	
$t_{\text{d(ON)}}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}, R_{\text{L}}=20\Omega, I_{\text{DS}}=1\text{A}, V_{\text{GEN}}=10\text{V}, R_{\text{G}}=6\Omega$	-	7.8	-	ns
t_{r}	Turn-on Rise Time		-	6.9	-	
$t_{\text{d(OFF)}}$	Turn-off Delay Time		-	22.4	-	
t_{f}	Turn-off Fall Time		-	4.8	-	
Gate Charge Characteristics ^d						
Q_{g}	Total Gate Charge	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{DS}}=6\text{A}$	-	15.7	22	nC
Q_{g}	Total Gate Charge	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=4.5\text{V}, I_{\text{DS}}=6\text{A}$	-	7.5	10.5	
Q_{gth}	Threshold Gate Charge		-	1.85	-	
Q_{gs}	Gate-Source Charge		-	3.24	-	
Q_{gd}	Gate-Drain Charge		-	2.75	-	

Note c : Pulse test ; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

Note d : Guaranteed by design, not subject to production testing.

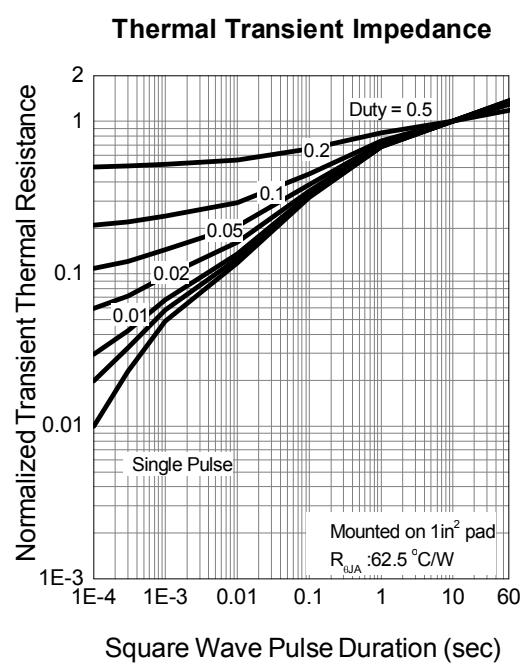
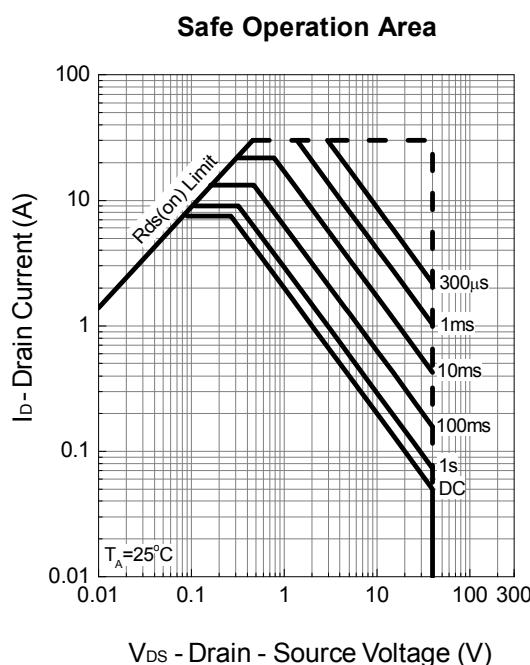
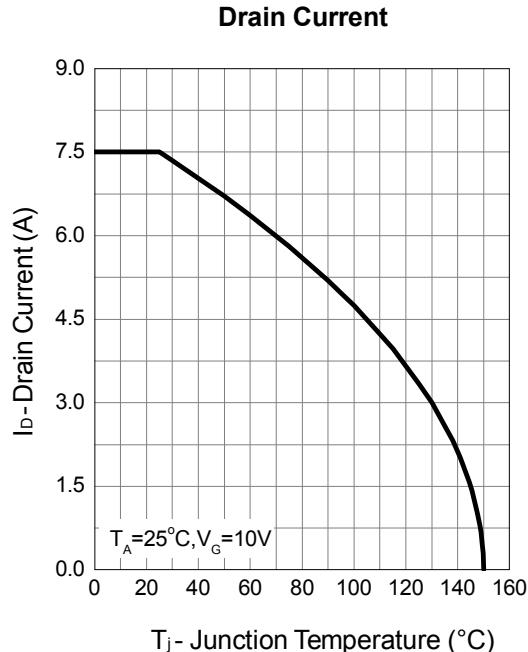
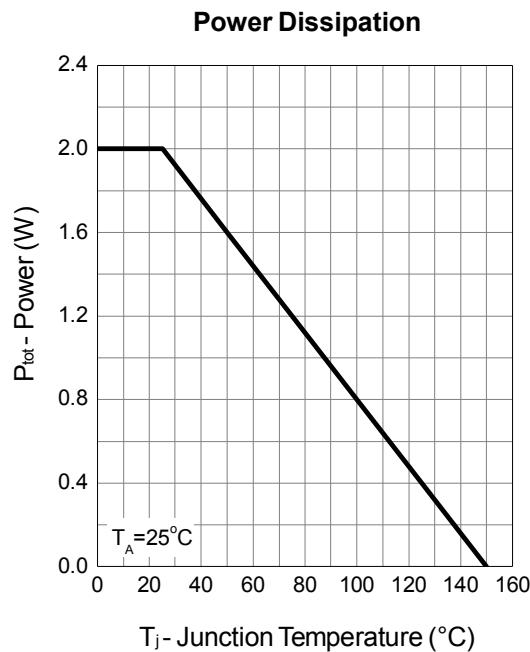
P Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	P Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=-250\mu\text{A}$	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-32\text{V}, V_{\text{GS}}=0\text{V}$ $T_J=85^\circ\text{C}$	-	-	-1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=-250\mu\text{A}$	-1.5	-2	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
$R_{\text{DS(ON)}}^{\text{c}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-5.5\text{A}$	-	30	38	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{DS}}=-3.5\text{A}$	-	46	62	
Diode Characteristics						
V_{SD}^{c}	Diode Forward Voltage	$I_{\text{SD}}=-1\text{A}, V_{\text{GS}}=0\text{V}$	-	-0.75	-1	V
t_{rr}	Reverse Recovery Time	$I_{\text{DS}}=-5.5\text{A},$ $dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	-	15	-	ns
Q_{rr}	Reverse Recovery Charge		-	8	-	nC
Dynamic Characteristics ^d						
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	8	-	Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V},$ $V_{\text{DS}}=-20\text{V},$ Frequency=1.0MHz	-	668	-	pF
C_{oss}	Output Capacitance		-	98	-	
C_{rss}	Reverse Transfer Capacitance		-	72	-	
$t_{\text{d(ON)}}$	Turn-on Delay Time	$V_{\text{DD}}=-20\text{V}, R_{\text{L}}=20\Omega,$ $I_{\text{DS}}=-1\text{A}, V_{\text{GEN}}=-10\text{V},$ $R_{\text{G}}=6\Omega$	-	8.7	-	ns
t_{r}	Turn-on Rise Time		-	7	-	
$t_{\text{d(OFF)}}$	Turn-off Delay Time		-	31	-	
t_{f}	Turn-off Fall Time		-	17	-	
Gate Charge Characteristics ^d						
Q_{g}	Total Gate Charge	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=-10\text{V},$ $I_{\text{DS}}=-5.5\text{A}$	-	15	-	nC
Q_{g}	Total Gate Charge	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=-4.5\text{V},$ $I_{\text{DS}}=-5.5\text{A}$	-	7.5	-	
Q_{gth}	Threshold Gate Charge		-	1.4	-	
Q_{gs}	Gate-Source Charge		-	2.4	-	
Q_{gd}	Gate-Drain Charge		-	3.5	-	

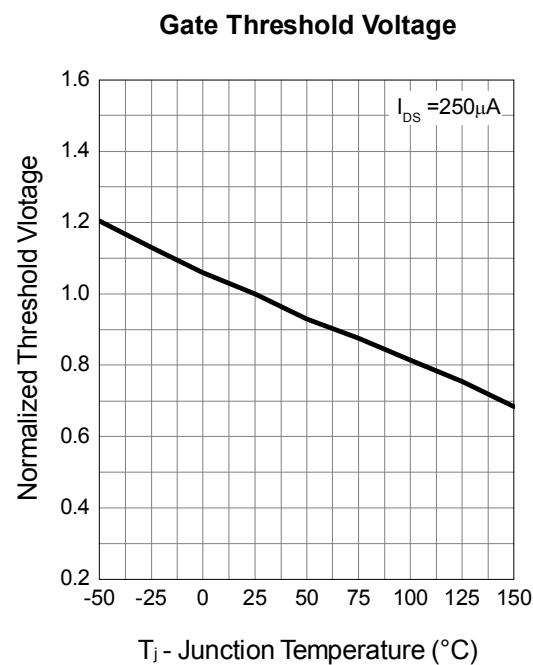
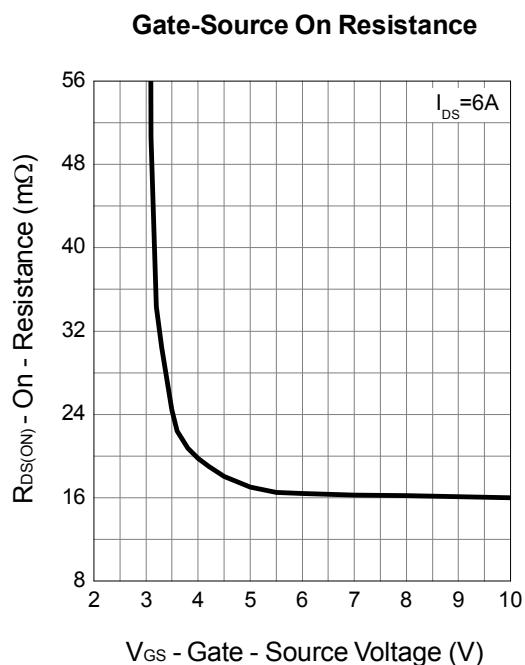
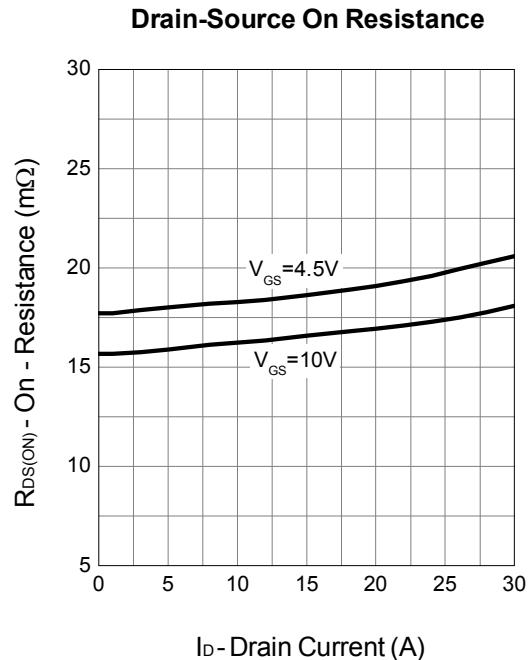
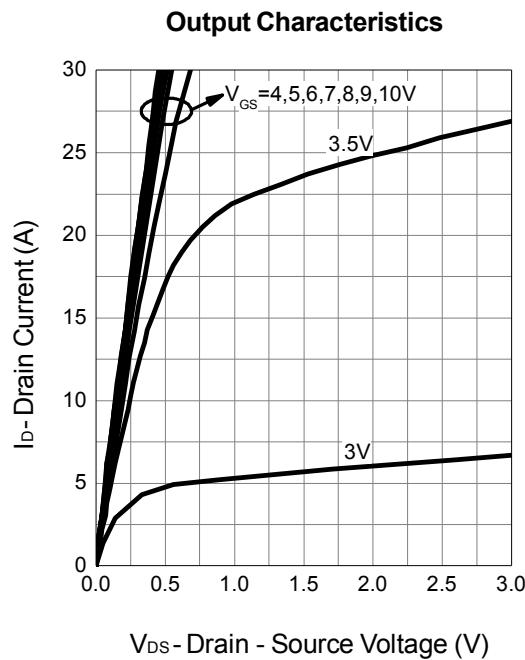
Note c : Pulse test; pulse width $\leq300\mu\text{s}$, duty cycle $\leq2\%$.

Note d : Guaranteed by design, not subject to production testing.

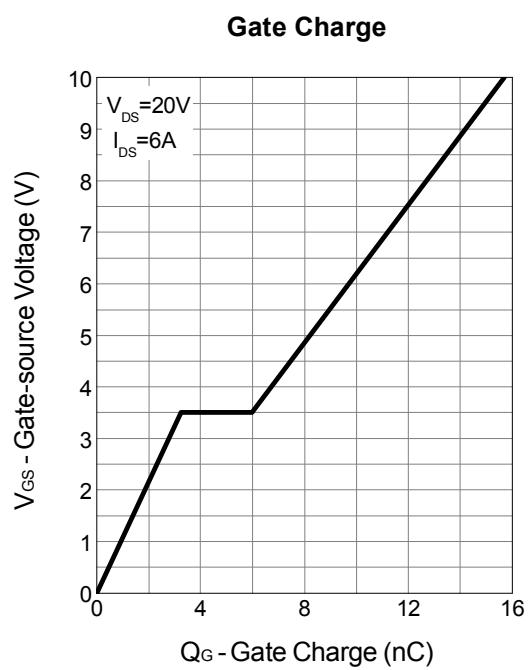
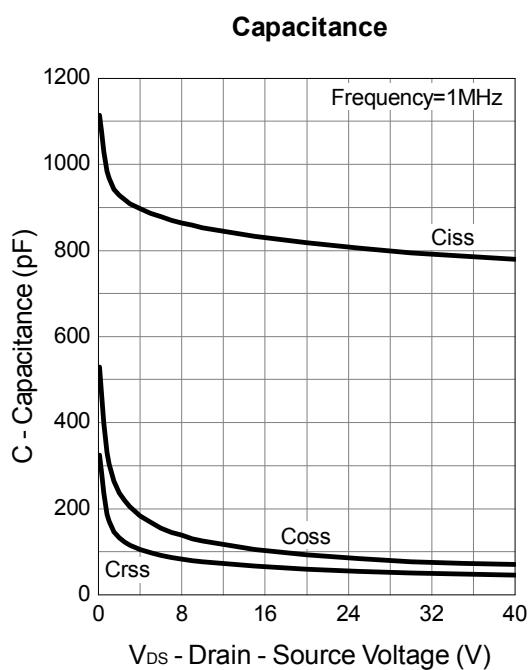
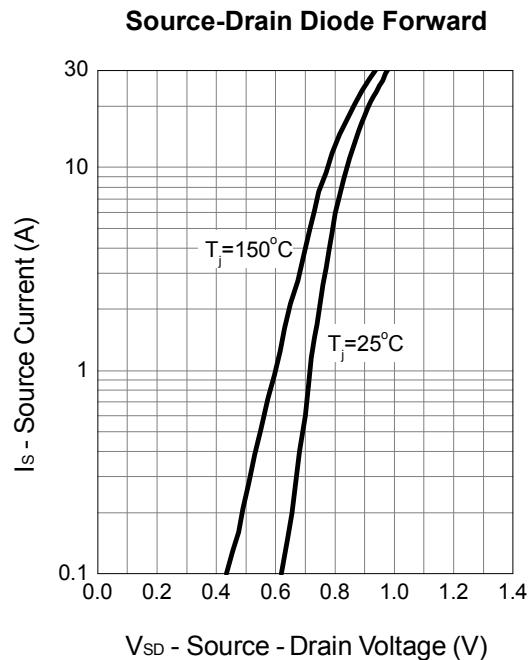
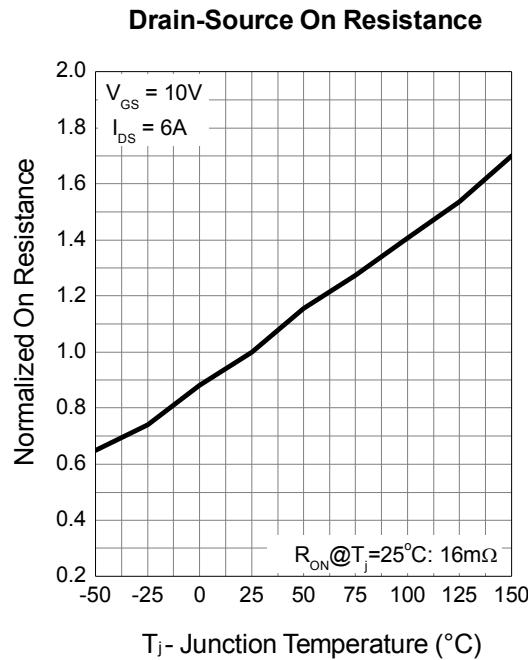
N Channel Typical Operating Characteristics



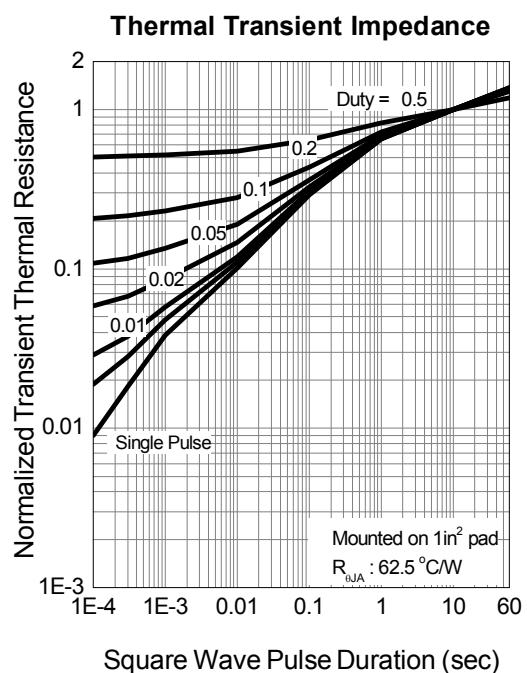
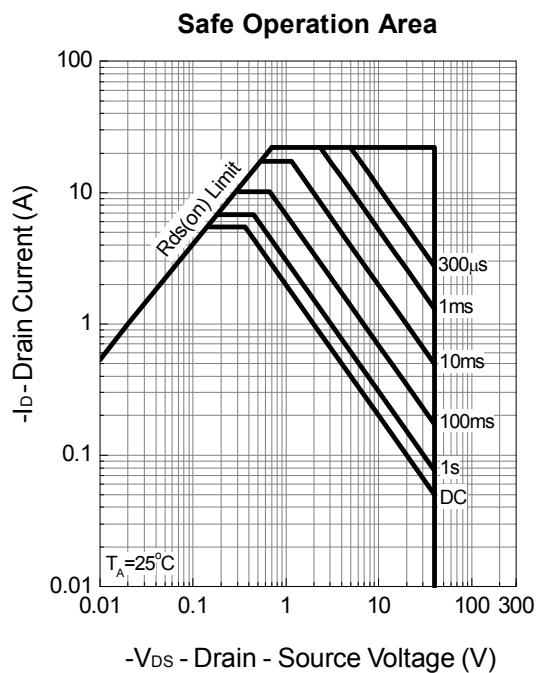
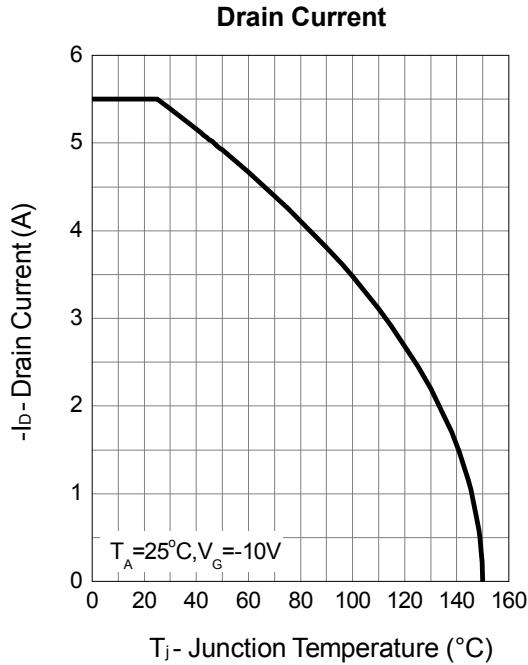
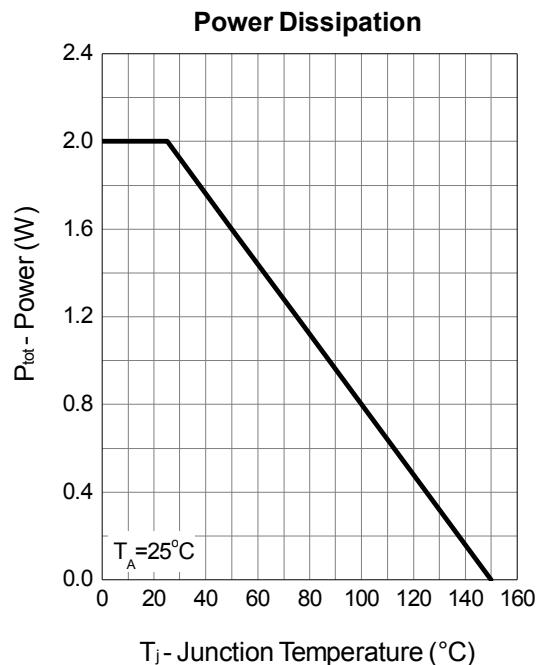
N Channel Typical Operating Characteristics (Cont.)



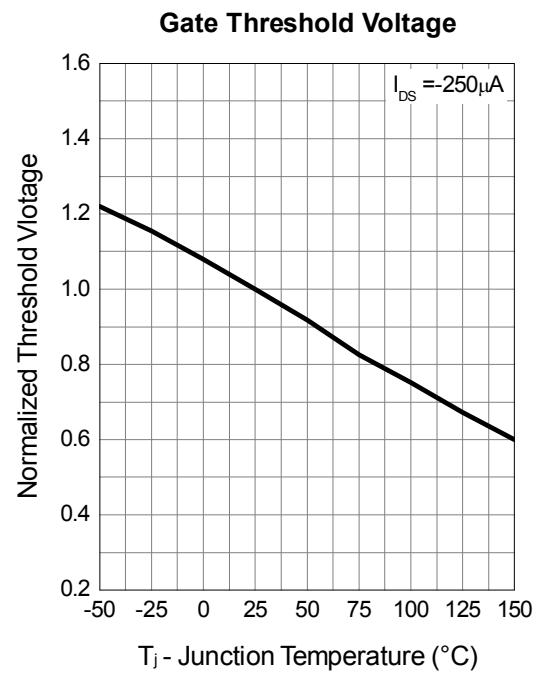
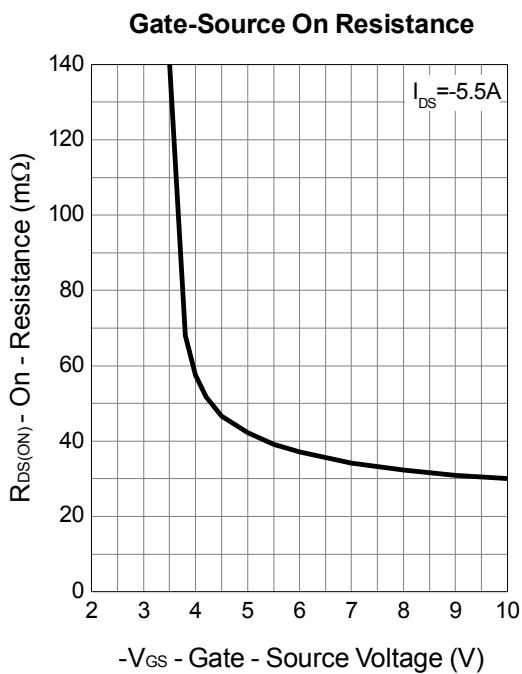
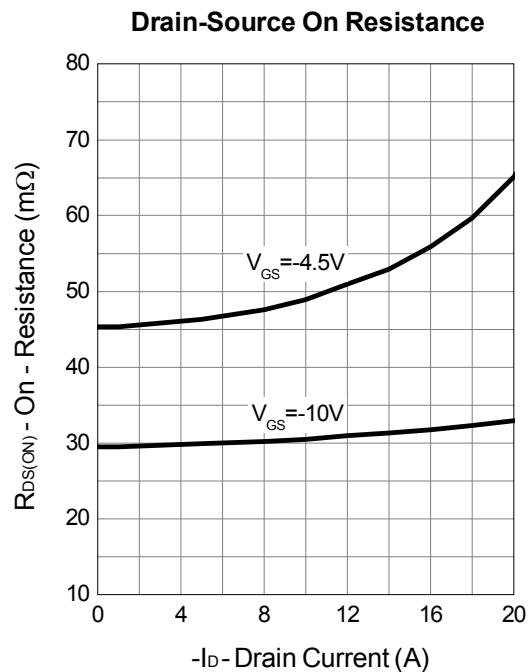
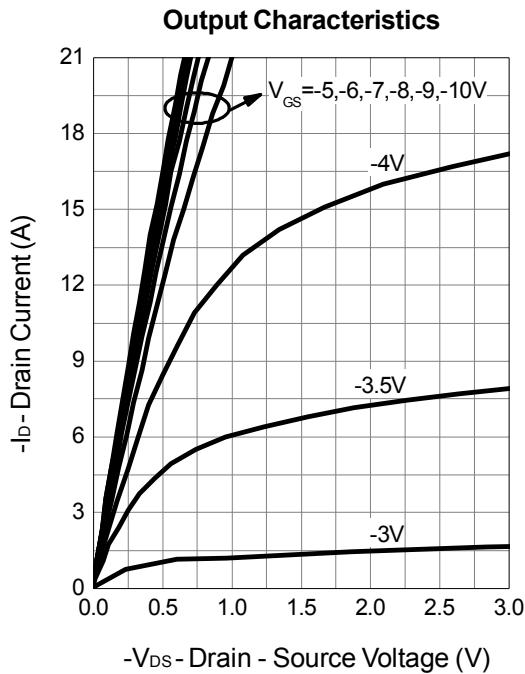
N Channel Typical Operating Characteristics (Cont.)



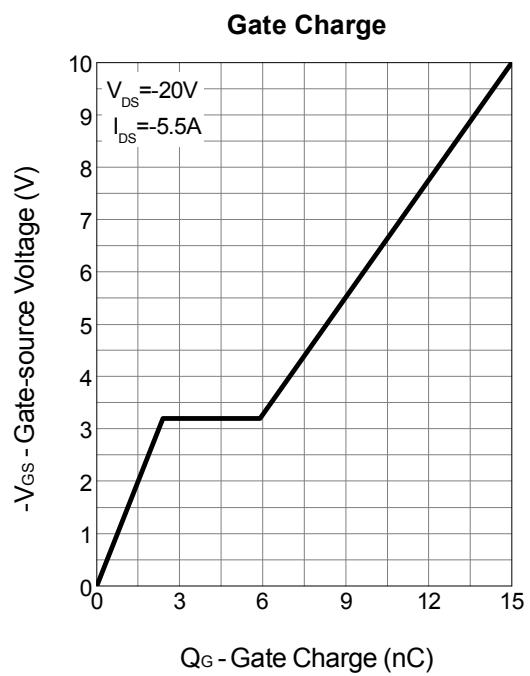
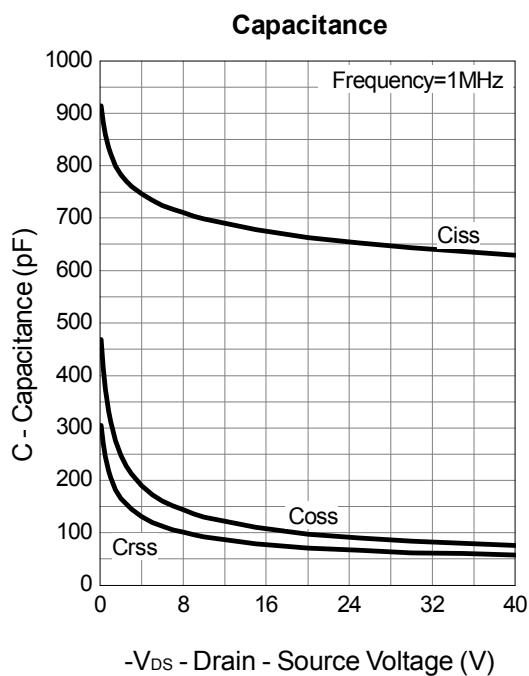
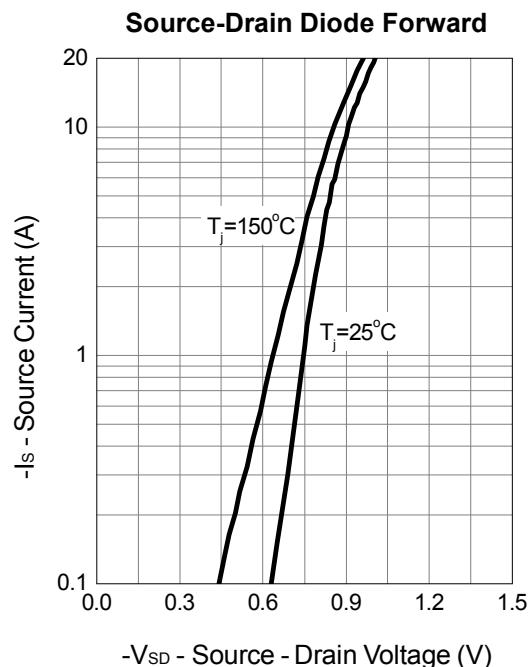
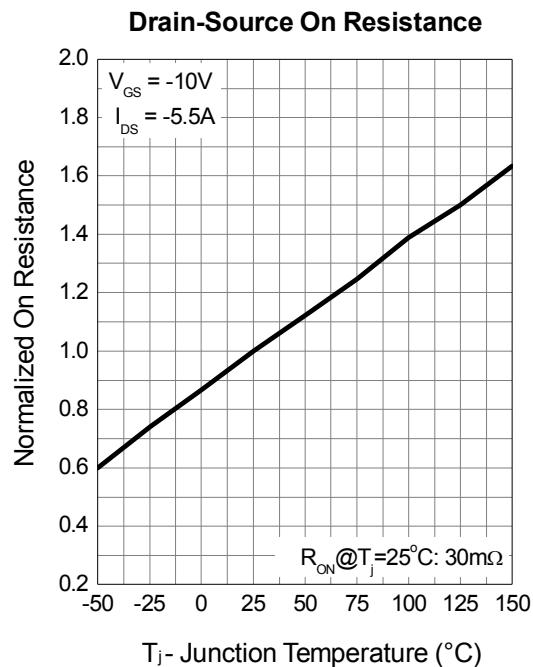
P Channel Typical Operating Characteristics



P Channel Typical Operating Characteristics (Cont.)

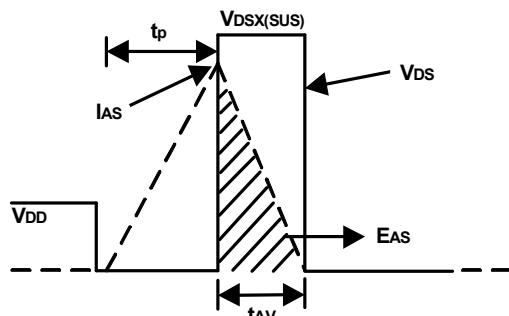
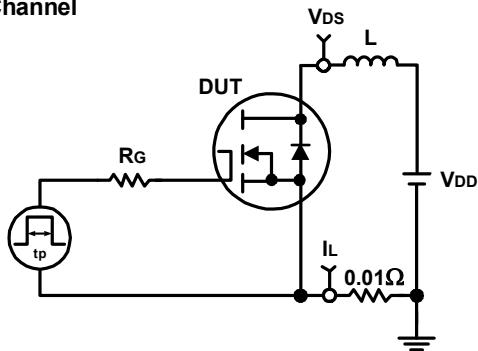


P Channel Typical Operating Characteristics (Cont.)

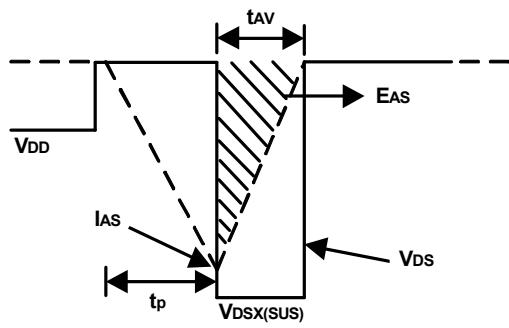
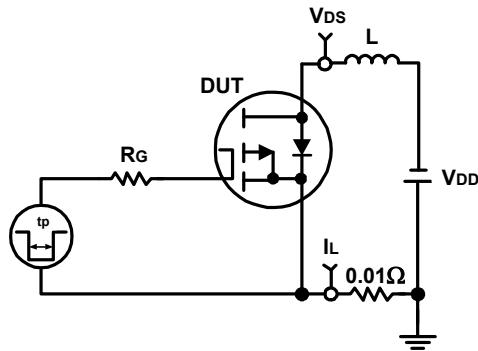


Avalanche Test Circuit and Waveforms

N Channel

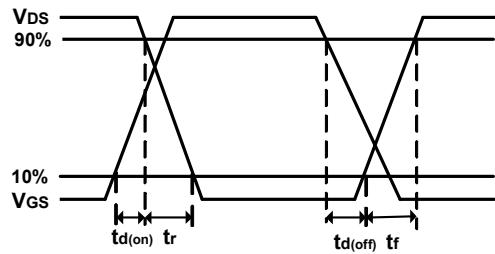
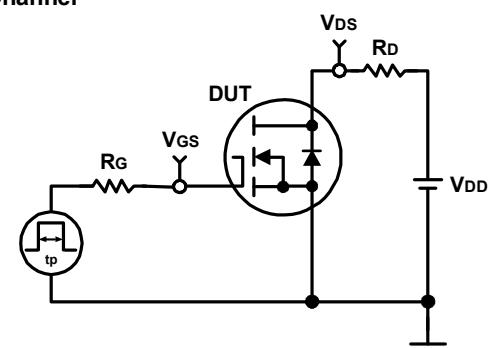


P Channel



Switching Time Test Circuit and Waveforms

N Channel



P Channel

